SPECIFICATION

SPEC. NO.： DG060082 REV： A

DATE： 07-Jul-2006

PRODUCT NAME： RJ45 1x1 Tab up
w/ Transformer & w/o LED

PRODUCT NO： P55-PZ1-1NM9(Lead Free)

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Product Number : P55-PZ1-1NM9(Lead Free)

Product Description : RJ45 1x1 Tab up w/ Transformer & w/o LED

1 SCOPE

1.1 Content

1.1.1 This specification covers performance, tests and quality requirements for RJ45 1x1 Tab up w/ Transformer & w/o LED.

2 APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

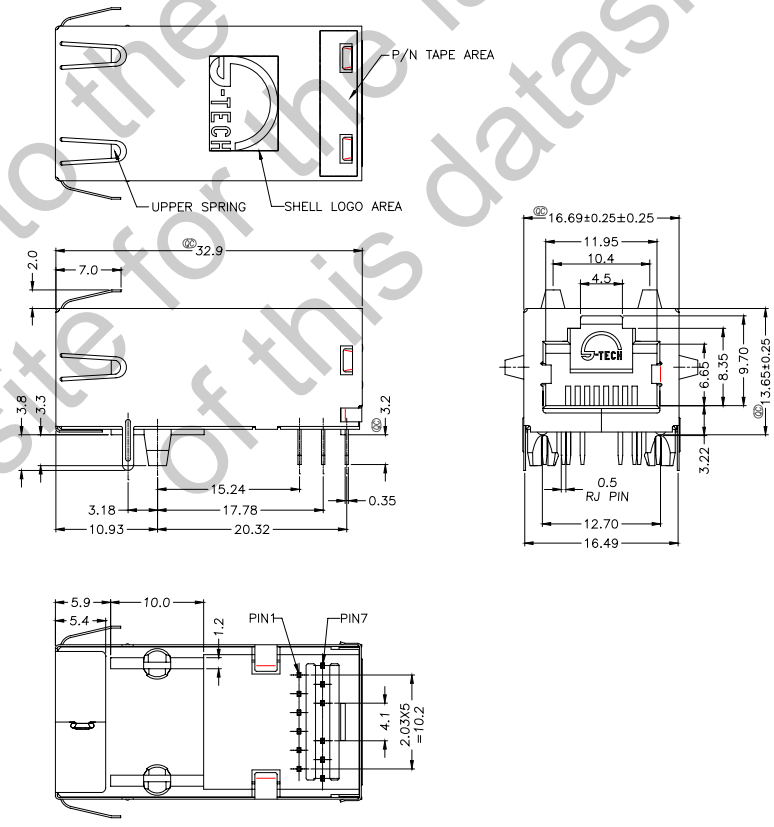
2.1 Commercial standards, specifications and report

2.1.1 MIL-STD-1344A

2.1.2 EIA-364

3 MECHANIC DIMENSIONS

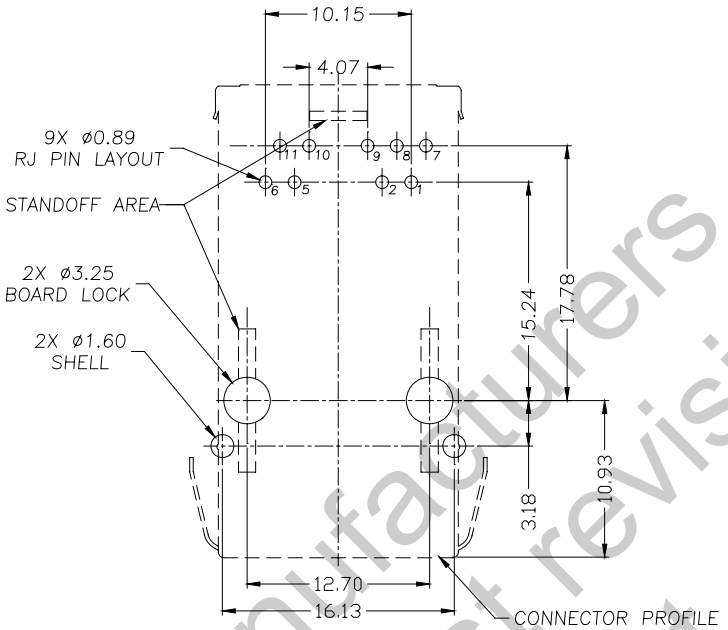
3.1 Dimensions



General Tolerance: . X : ±0.38

. XX : ±0.25

3.2 PCB Layout



RECOMMENDED PCB LAYOUT
COMPONENT SIDE

ALL DIMENSION TOLERANCE ARE ±0.05mm
UNLESS OTHERWISE SPECIFIED

4 REQUIREMENTS

4.1 Design and Construction

4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact :

4.2.1.1 RJ Contact : Phosphor Bronze

Finish : (a) Contact Area : 30 μ" min. Gold

(b) Solder tail Area : 100 μ" min. Matted Tin

(c) Underplating : 50~100 μ" Nickel over all

4.2.1.2 Joint Contact : Brass

Finish : Gold flash or 100 μ" min. Matted Tin&50~100 μ" Nickel over all

4.2.2 Plastic Part :

4.2.2.1 Housing : Thermoplastic , PA46 , Black

Flame Class : UL94 V-0

4.2.2.2 Case : Thermoplastic , PA46 , Black

Flame Class : UL94 V-0

4.2.3 Shell

4.2.3.1 Front Shell : Brass

Finish : 120 μ" min. Nickel over

4.2.3.2 Back Shell : Stainless steel, SUS304

4.2.4 Transformer

4.2.4.1 Material : FR4,

4.2.4.2 Two Layer PCB

4.3 Operating and Storage Temperature

4.3.1 Operating Temperature : 0℃ TO +70℃

4.3.2 Non-Operating Temperature : -40℃ TO +85℃

4.4 Ratings

4.4.1 Voltage rating : 125 VAC

4.4.2 Current rating : 1.5 A

4.5 Performance and Test Description

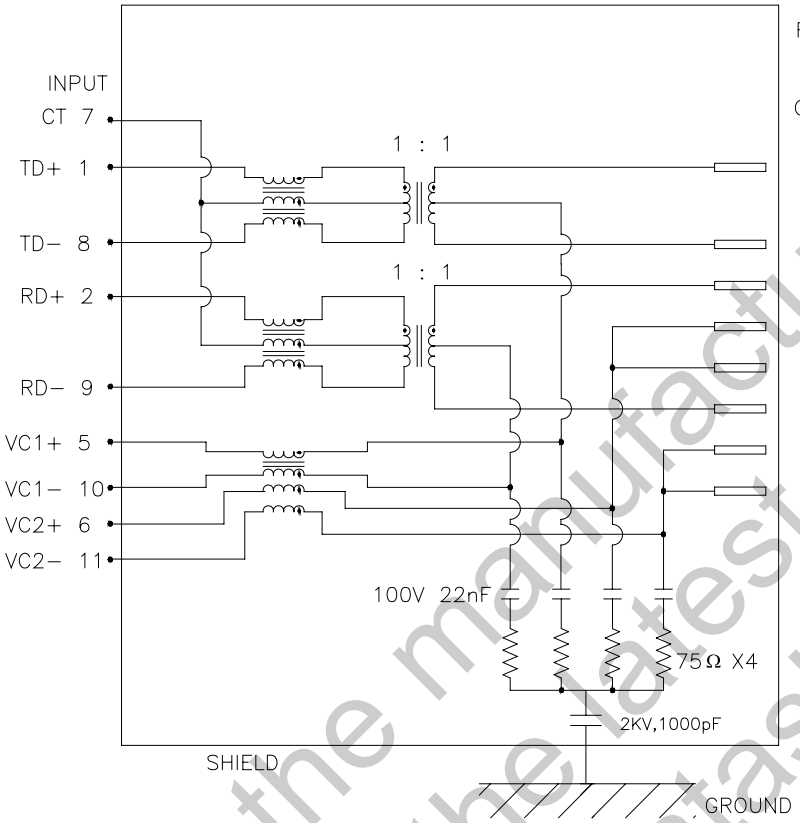
Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

4.6 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

5 ELECTRICAL CHARACTERISTICS

5.1 Schematic



5.2 Transmitter filter & Receiver filter

Type : Balance low pass 100Ω impedance

Insertion loss : 1~100 MHz –1.0dB MAX.

Return loss: 1~30 MHz –18dB MIN. load 100Ω

30~60 MHz –16dB MIN. load 100Ω

60~80 MHz –12dB MIN. load 100Ω

5.3 Common Mode Rejection

@ 1~100 MHz –30dB MIN.

5.4 Cross Talk

@ 1~100 MHz –35dB MIN

5.5 INDUCTANCE @ 100KHz, 0.1V, 8mA DC BIAS

Input(1-8), Input(2-9): 350 μH MIN.

5.6 Hi Pot TEST

Input(1-8) to Output(1-2) : 1500VAC, 60sec

Input(2-9) to Output(3-6) : 1500VAC, 60sec

6 ORDER INFORMATION

P 5 5 - P X X - X XX X
A B C D E

P: Lead Free

A：LED Code

W/O LED：**Z**		Right LED				
		Yellow	Green	Orange	G/O	G/Y
Left LED	Yellow	0	4	8	C	H
	Green	1	5	9	D	J
	Orange	2	6	A	F	K
	G/O	3	7	B	G	M
	G/Y	N	P	Q	R	S

B：Grounding Spring Code

0：w/o All Grounding Spring

1：w/ All Grounding Spring

2：w/ Top Grounding Spring Only

C：Logo Code

0：w/o Speed Tech Logo

1：w/ Speed Tech Logo

D：Schematic Code

NM：NM Type Circuit

E：Contact Plating Code

0：Tin/Lead 100 μ”

6：1~3 μ” Gold on Contact Area

7：10 μ” minimum Gold on Contact Area

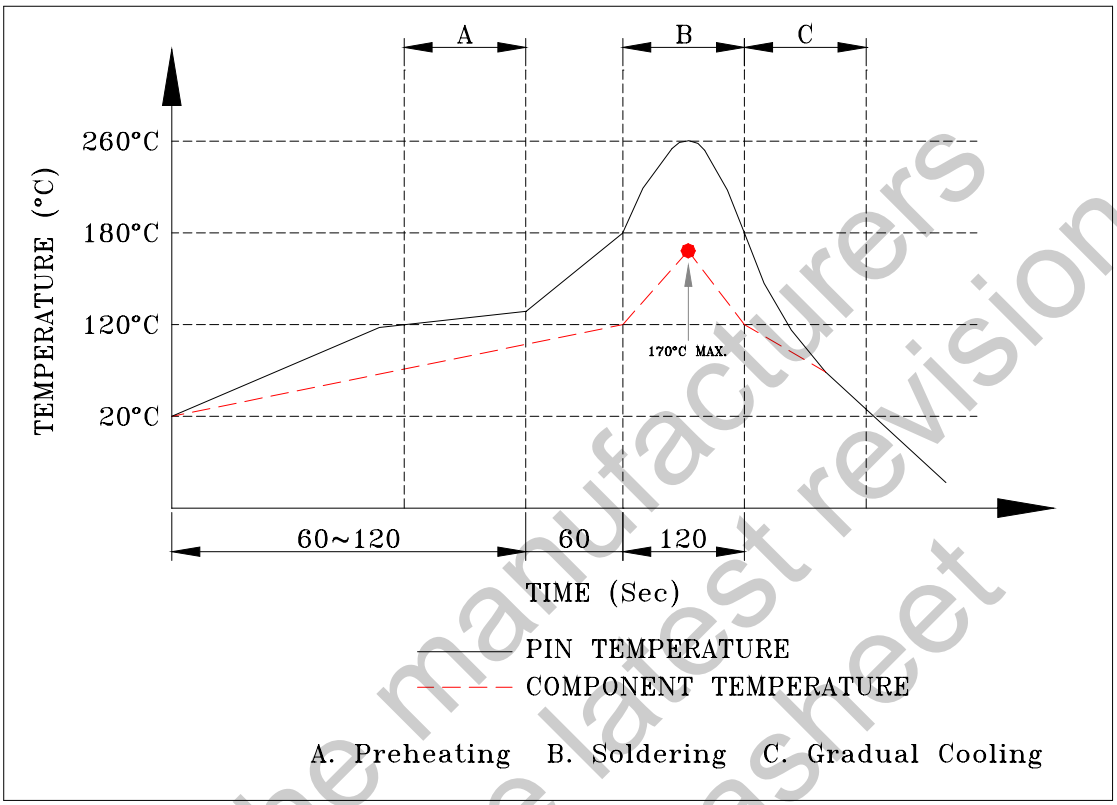
8：15 μ” minimum Gold on Contact Area

9：30 μ” minimum Gold on Contact Area

A：50 μ” minimum Gold on Contact Area

7 Profile of Wave Solder

7.1 PROFILE OF WAVE SOLDER



SUGGESTED WAVE SOLDER CURVE

(1)Tip temperature : 260±10°C

(2)Tip temperature time : 5sec max

***The melting point of Sn96.5/Ag3/Cu0.5 : 217℃**